



QUAD/DUAL SUPERCAPACITOR AUTO BALANCING (SAB™) MOSFET ARRAY

GENERAL DESCRIPTION

The ALD810028/ALD910028 are members of the ALD8100xx (quad) and ALD9100xx (dual) family of Supercapacitor Auto Bal-ancing MOSFETs, or SAB™ MOSFETs. SAB MOSFETs are built with production proven EPAD® technology and are designed to address voltage and leakage-current balancing of supercapacitors connected in series. Supercapacitors, also known as ultracapacitors or supercaps, connected in series can be leakage-current balanced by using a combination of one or more devices connected across each supercapacitor stack to prevent over-voltages.

The ALD810028 offers a set of unique, precise operating voltage and current characteristics for each of four SAB MOSFET devices, as shown in its Operating Electrical Characteristics table. It can be used to balance up to four supercapacitors connected in series. The ALD910028 has its own set of unique precision Operating Electrical Characteristics for each of its two SAB MOSFET devices, suitable for up to two series-connected supercapacitors.

Each SAB MOSFET features a precision gate threshold voltage in the Vt mode, which is 2.80V when the gate-drain source terminals $(V_{GS} = V_{DS})$ are connected together at a drain-source current of $I_{DS(ON)} = 1\mu A$. In this mode, input voltage $V_{IN} = V_{GS} = V_{DS}$. Different VIN produces an Output Current IOUT = IDS(ON) characteristic and results in an effective variable resistor that varies in value exponentially with VIN. This VIN, when connected across each supercapacitor in a series, balances each supercapacitor to within its voltage and current limits.

When VIN = 2.80V is applied to an ALD810028/ALD910028, its IOUT is 1µA. For a 100mV increase in VIN, to 2.90V, IOUT increases by about tenfold. For an additional increase in V_{IN} to 3.02V for the ALD910028 (3.04V for the ALD810028), IOUT increases one hundredfold, to 100µA. Conversely, for a 100mV decrease in VIN to 2.70V, IOUT decreases to one tenth of its previous value, to 0.1µA. Another 100mV decrease in input voltage would reduce IOUT to 0.01µA. Hence, when an ALD810028/ALD910028 SAB MOSFET is connected across a supercapacitor that charges to less than 2.60V, it would dissipate essentially no power.

(Continued on next page)

PRODUCT FAMILY SPECIFICATIONS

For more information on supercapacitor balancing, how SAB MOSFETs achieve automatic supercapacitor balancing, the device characteristics of the SAB MOSFET family, product family product selection guide, applications, configurations, and package information, please download from www.aldinc.com the document:

"ALD8100xx/ALD9100xx Family of Supercapacitor Auto Balancing (SAB[™]) MOSFET ARRAYs"

ORDERING INFORMATION ("L" suffix denotes lead-free (RoHS))

	Operating Temperature Range				
Package	0°C to +70°C	-40°C to +85°C			
	(Commercial)	(Industrial)			
16-Pin SOIC	ALD810028SCL	ALD810028SCLI			
8-Pin SOIC	ALD910028SAL	ALD910028SALI			

FEATURES & BENEFITS

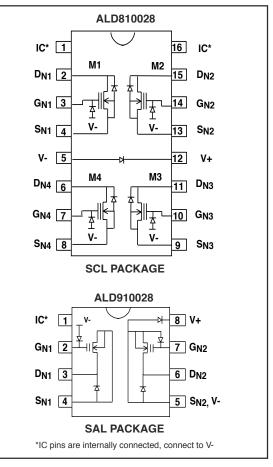
- · Simple and economical to use
- Precision factory trimmed
- Automatically regulates and balances leakage currents
- Effective for supercapacitor charge-balancing
- Balances up to 4 supercaps with a single IC package
- Balances 2-cell, 3-cell, 4-cell series-connected supercaps
- Scalable to larger supercap stacks and arrays Near zero additional leakage currents Zero leakage at 0.3V below rated voltages

- Balances series and/or parallel-connected supercaps
- Leakage currents are exponential function of cell voltages
- Active current ranges from <0.3nA to >1000μA
- · Always active, always fast response time
- · Minimizes leakage currents and power dissipation

APPLICATIONS

- · Series-connected supercapacitor cell leakage balancing
- Energy harvesting
- Long term backup battery with supercapacitor outputs
- Zero-power voltage divider at selected voltages
- Matched current mirrors and current sources
- Zero-power mode maximum voltage limiter
- · Scaled supercapacitor stacks and arrays

PIN CONFIGURATIONS



GENERAL DESCRIPTION (CONT.)

The voltage dependent characteristic of the ALD810028/ ALD910028 on-resistance is effective in controlling excessive voltage rise across a supercapacitor when connected across it. In series-connected supercapacitor stacks, when one supercapacitor voltage rises, the voltage of the other supercapacitors drops, with the ones that have the highest leakage currents having the lowest supercapacitor voltages. The SAB MOSFETs connected across these supercapacitors would exhibit complementary opposing current levels, resulting in little additional leakage currents other than those caused by the supercapacitors themselves.

For technical assistance, please contact ALD technical support at techsupport@aldinc.com.

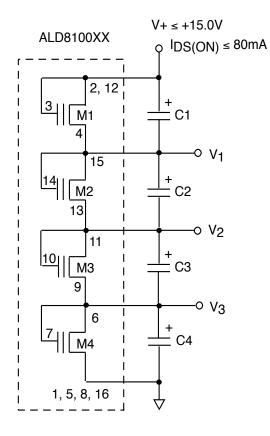
APPLYING THE ALD810028/ALD910028:

1) Select a maximum supercapacitor leakage current limit for any supercapacitor used in the stack. This is the same as output current, $I_{OUT} = I_{DS(ON)}$, of the ALD810028/ALD910028. Test that each supercapacitor leakage current meets this maximum current limit before use in the stack.

2) Determine whether the input voltage V_{IN} (V_{GS} = V_{DS}) at that I_{OUT} is acceptable for the intended application. This voltage is the same voltage as the maximum desired operating voltage of the supercapacitor. For example, with the ALD810028, I_{OUT} = 0.1μ A corresponds to V_{IN} = 2.70V.

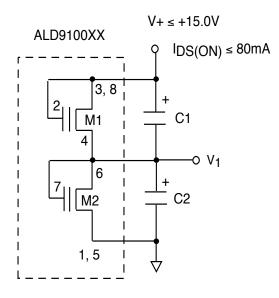
3) Determine that the operating voltage margin, due to various tolerances and/or temperature effects, is adequate for the intended operating environment of the supercapacitor.

SCHEMATIC DIAGRAM OF A TYPICAL CONNECTION FOR A FOUR-SUPERCAP STACK



1-16 DENOTES PACKAGE PIN NUMBERS C1-C4 DENOTES SUPERCAPACITORS

SCHEMATIC DIAGRAM OF A TYPICAL CONNECTION FOR A TWO-SUPERCAP STACK



1-8 DENOTES PACKAGE PIN NUMBERS C1-C2 DENOTES SUPERCAPACITORS

ABSOLUTE MAXIMUM RATINGS

V+ to V- voltage	15.0V
Drain-Source voltage, V _{DS}	10.6V
Gate-Source voltage, V _{GS}	10.6V
Operating Current	80mA
Power dissipation	
Operating temperature range SCL	0°C to +70°C
Operating temperature range SCLI	
Storage temperature range	
Lead temperature, 10 seconds	+260°C
CAUTION: ECD Consistive Device. Use static control presedures in ECC	Security all and subject was not

CAUTION: ESD Sensitive Device. Use static control procedures in ESD controlled environment.

OPERATING ELECTRICAL CHARACTERISTICS

V + = +5V, V - = GND,	ΤA = 25°C,	$V_{IN} = V_{GS} = V_{DS}$	IOUT = IDS(ON)	unless otherwise specified
-----------------------	-------------------	----------------------------	----------------	----------------------------

	ALD810028					
Parameter	Symbol	Min	Тур	Мах	Unit	Test Conditions
Gate Threshold Voltage	Vt	2.78	2.80	2.82	V	VGS = VDS; IDS(ON) = 1µA
Offset Voltage	VOS		5	20	mV	V _{t1} - V _{t2} or V _{t3} - V _{t4}
Offset Voltage Tempco	TCVOS		5		μV/C	V _{t1} - V _{t2} or V _{t3} - V _{t4}
Gate Threshold Voltage Tempco	TCVt		-2.2		mV/C	$V_{GS} = V_{DS}; I_{DS(ON)} = 1 \mu A$
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.0001 24000		μΑ ΜΩ	V _{IN} = 2.40V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.001 2500		μΑ ΜΩ	V _{IN} = 2.50V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.01 260		μΑ ΜΩ	VIN = 2.60V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.1 27		μΑ ΜΩ	V _{IN} = 2.70V
Output Current Drain Source On Resistance	IOUT RDS(ON)		1 2.8		μΑ ΜΩ	V _{IN} = 2.80V
Output Current Drain Source On Resistance	IOUT RDS(ON)		10 0.29		μΑ ΜΩ	V _{IN} = 2.90V
Output Current Drain Source On Resistance	IOUT RDS(ON)		100 0.030		μΑ ΜΩ	VIN = 3.04V
Output Current Drain Source On Resistance	IOUT RDS(ON)		300 0.01		μΑ ΜΩ	VIN = 3.14V
Output Current Drain Source On Resistance	IOUT RDS(ON)		1000 0.003		μΑ ΜΩ	V _{IN} = 3.32V
Output Current Drain Source On Resistance	I _{OUT} RDS(ON)		3000 0.001		μΑ ΜΩ	V _{IN} = 3.62V
Output Current Drain Source On Resistance	IOUT RDS(ON)		10000 0.0004		μΑ ΜΩ	V _{IN} = 4.22V
Drain Source Breakdown Voltage	BVDSX	10.6			V	
Drain Source Leakage Current ¹	IDS(OFF)		10	400 4	pA nA	$V_{IN} = V_{GS} = V_{DS} = V_t - 1.0$ $V_{IN} = V_{GS} = V_{DS} = V_t - 1.0,$ $T_A = +125^{\circ}C$
Gate Leakage Current ¹	IGSS		5	200	pA nA	$V_{GS} = 5.0V, V_{DS} = 0V$ $V_{GS} = 5.0V, V_{DS} = 0V,$ $T_{A} = +125^{\circ}C$
Input Capacitance	CISS		15		pF	V _{GS} = 0V, V _{DS} = 5.0V
Turn-on Delay Time	ton		10		ns	
Turn-off Delay Time	^t off		10		ns	
Crosstalk			60		dB	f = 100KHz

ABSOLUTE MAXIMUM RATINGS

V+ to V- voltage	15.0V
Drain-Source voltage, V _{DS}	10.6V
Gate-Source voltage, V _{GS}	10.6V
Operating Current	80mA
Power dissipation	500mW
Operating temperature range SAL	0°C to +70°C
Operating temperature range SALI	40°C to +85°C
Storage temperature range	
Lead temperature, 10 seconds	
CALITION: ESD Sensitive Device, Use static control precedures in I	

CAUTION: ESD Sensitive Device. Use static control procedures in ESD controlled environment.

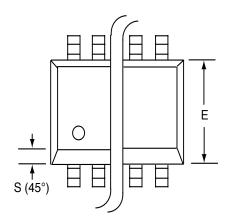
OPERATING ELECTRICAL CHARACTERISTICS

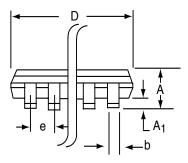
$V = +5V, V = GND, T_A =$	$= 25^{\circ}C, V_{IN} = V$	/gs=Vds, lout=	= IDS(ON) unless	otherwise specified
---------------------------	-----------------------------	----------------	------------------	---------------------

	ALD910028					
Parameter	Symbol	Min	Тур	Мах	Unit	Test Conditions
Gate Threshold Voltage	Vt	2.78	2.80	2.82	v	$V_{GS} = V_{DS}; I_{DS(ON)} = 1 \mu A$
Offset Voltage	VOS		5	20	mV	V _{t1} - V _{t2}
Offset Voltage Tempco	TCVOS		5		μV/C	V _{t1} - V _{t2}
Gate Threshold Voltage Tempco	TC _{Vt}		-2.2		mV/C	$V_{GS} = V_{DS}; I_{DS(ON)} = 1 \mu A$
Output Current Drain Source On Resistance	lout Rds(on)		0.0001 24000		μΑ ΜΩ	VIN = 2.40V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.001 2500		μΑ ΜΩ	V _{IN} = 2.50V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.01 260		μΑ ΜΩ	V _{IN} = 2.60V
Output Current Drain Source On Resistance	IOUT RDS(ON)		0.1 27		μΑ ΜΩ	V _{IN} = 2.70V
Output Current Drain Source On Resistance	lout Rds(on)		1 2.8		μΑ ΜΩ	V _{IN} = 2.80V
Output Current Drain Source On Resistance	IOUT RDS(ON)		10 0.29		μΑ ΜΩ	V _{IN} = 2.90V
Output Current Drain Source On Resistance	IOUT RDS(ON)		100 0.030		μΑ ΜΩ	V _{IN} = 3.02V
Output Current Drain Source On Resistance	IOUT RDS(ON)		300 0.01		μΑ ΜΩ	V _{IN} = 3.10V
Output Current Drain Source On Resistance	lout Rds(on)		1000 0.003		μΑ ΜΩ	V _{IN} = 3.24V
Output Current Drain Source On Resistance	IOUT RDS(ON)		3000 0.001		μΑ ΜΩ	V _{IN} = 3.30V
Output Current Drain Source On Resistance	IOUT RDS(ON)		10000 0.0004		μΑ ΜΩ	V _{IN} = 3.80V
Drain Source Breakdown Voltage	BV _{DSX}	10.6			v	
Drain Source Leakage Current ¹	IDS(OFF)		10	400	pA nA	$V_{IN} = V_{GS} = V_{DS} = V_t - 1.0$ $V_{IN} = V_{GS} = V_{DS} = V_t - 1.0$, $T_A = +125^{\circ}C$
Gate Leakage Current ¹	IGSS		5	200 1	pA nA	$V_{GS} = 5.0V, V_{DS} = 0V$ $V_{GS} = 5.0V, V_{DS} = 0V,$ $T_A = +125^{\circ}C$
Input Capacitance	CISS		30		pF	VGS = 0V, VDS = 5.0V
Turn-on Delay Time	ton		10		ns	
Turn-off Delay Time	toff		10		ns	
Crosstalk			60		dB	f = 100KHz

SOIC-16 PACKAGE DRAWING

16 Pin Plastic SOIC Package





	Millim	neters	Inches		
Dim	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.25	0.004	0.010	
b	0.35	0.45	0.014	0.018	
С	0.18	0.25	0.007	0.010	
D-16	9.80	10.00	0.385	0.394	
Е	3.50	4.05	0.140	0.160	
е	1.27 BSC		0.050 BSC		
н	5.70	6.30	0.224	0.248	
L	0.60	0.937	0.024	0.037	
Ø	0°	8°	0°	8°	
s	0.25	0.50	0.010	0.020	

